

Title (en)

TREATMENT FLUID SUCTION DEVICE AND ETCHING APPARATUS USING THIS DEVICE

Title (de)

BEHANDLUNGSFLUID-ABSAUGVORRICHTUNG UND DIESE ENTHALTENDE ÄTZVORRICHTUNG

Title (fr)

DISPOSITIF D'ASPIRATION D'UN LIQUIDE DE TRAITEMENT ET APPAREIL DE GRAVURE UTILISANT CE DISPOSITIF

Publication

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Application

EP 16785116 A 20161019

Priority

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Abstract (en)

[origin: WO2017076640A1] The invention relates to an extracting device for extracting a treatment fluid from a substantially planar treatment surface (3a) of treatment substrates (3) transported by means of transporting rollers (8, 10) along a substantially horizontal transporting direction, comprising a suction source, an extraction control unit activating the latter, and an extraction tube unit connected to the suction source and having at least one extraction lance, which can be positioned with one or more inlet-side extraction nozzle openings at an extracting distance from the treatment surface. The invention also relates to an etching device equipped with such an extracting device. In the case of an extracting device according to the invention, the suction source and the extraction control unit are designed for a suction volume flow for each extraction lance of at least 30 m³/h and a suction vacuum of no more than 8 kPa. In addition or as an alternative, the extraction lance has a comb-like extraction structure with an extraction collecting tube (17) and a number of extraction tubes (18) that extend from the extraction collecting tube in a comb-like manner and have the extraction nozzle openings (19) on the inlet side. Use for example for etching printed circuit boards, conductor films or semiconductor wafers.

IPC 8 full level

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Citation (search report)

See references of WO 2017076640A1

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